MULTI-INNO TECHNOLOGY CO., LTD.

www.multi-inno.com

LCD MODULE SPECIFICATION

Model : MI0430K1T-2

For Customer's Acceptance:

Customer	
Approved	
Comment	

Revision	1.4
Engineering	
Date	2013-05-07
Our Reference	

REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
1.0	2012-05-15	First release	
1.1	2012-09-14	Updating the viewing erea size of cover lens.	
1.2	2012-11-22	Add CTP outline drawing	
1.3	2013-03-25	Update surface luminance Add application circuit notes	
1.4	2013-05-07	Add pixel pitch Change operating temperature and storage temperature	

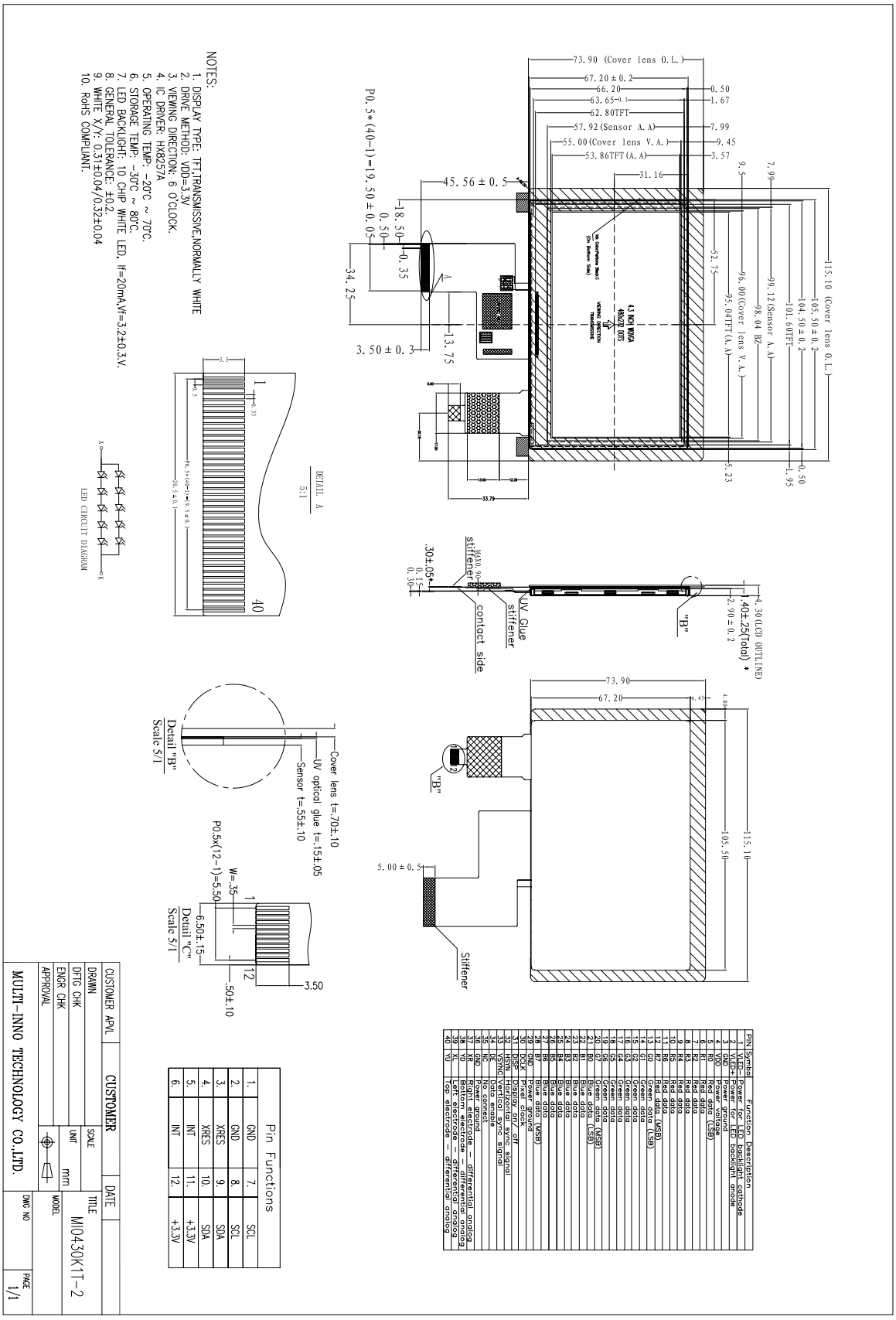
CONTENTS

■ GENERAL INFORMATION

Item	Contents	Unit/Note
LCD type	TFT/Transmissive/Normally white	/
Size	4.30	Inch
Viewing direction	6:00	O'Clock
Gray scale inversion direction	12:00	O'Clock
Module area (W × H)	115.10×73.90×4.30	mm^3
Active area (W×H)	95.04×53.86	mm^2
Pixel pitch (W×H)	0.066×0.198	mm^2
Number of Dots	480(RGB)×272	/
DriverIC	HX8257A	/
Colors	16.7M	/
Backlight Type	10 LEDs	/
Module Power consumption	TBD	mw
InterfaceType	24bit RGB	/
Input voltage	3.3	V
Weight	TBD	g
With/Without TSP	With CTP	/

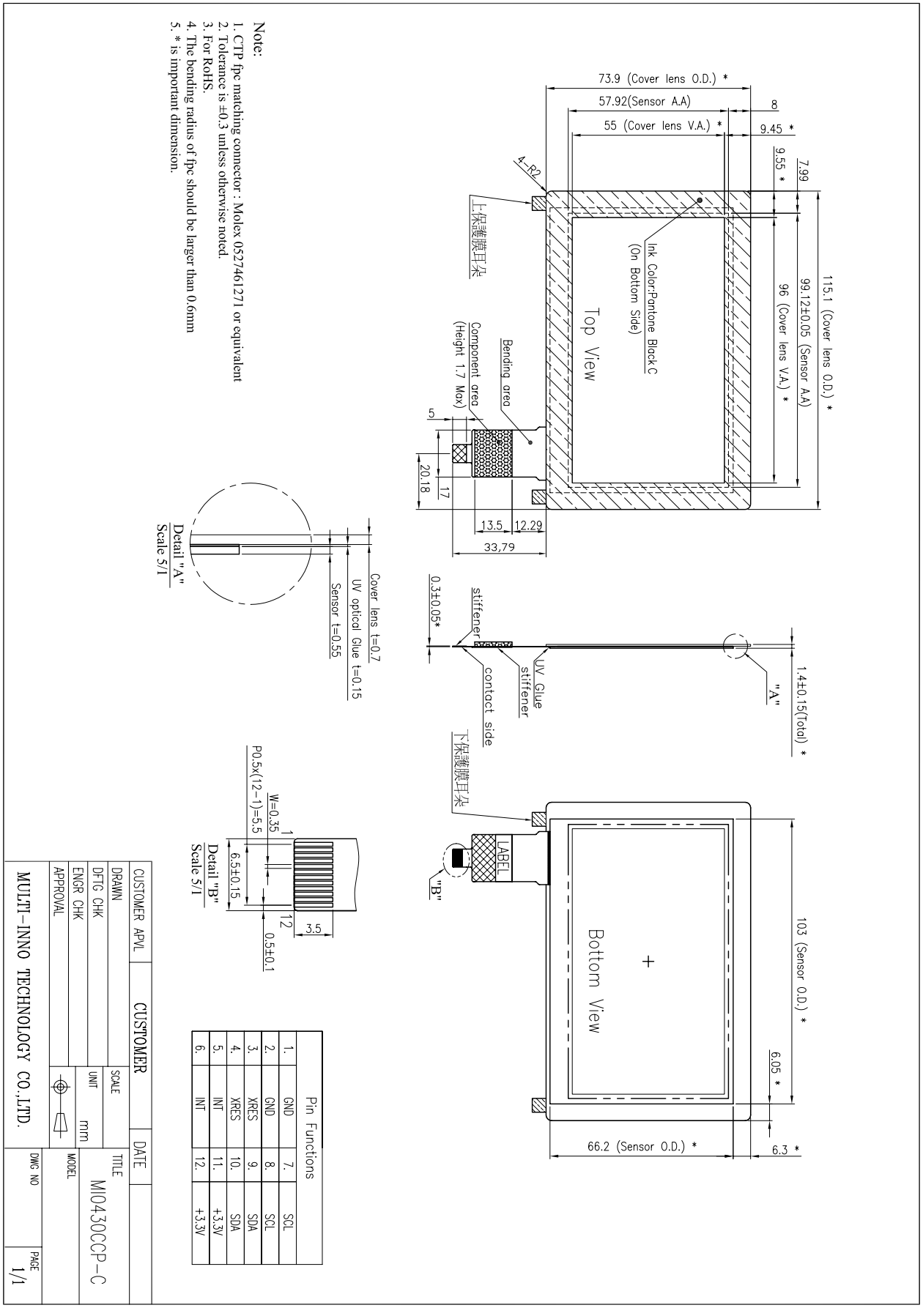
Note 1:Viewing direction for best image quality is different from TFT definition, there is a 180 degree shift.
Note 2 : RoHS compliant;
Note 3: LCM weight tolerance: ± 5% .

■ EXTERNAL DIMENSIONS



PIN	Symbol	Function Description
1	LED-	Power for LED backlight cathode
2	VLED+	Power for LED backlight anode
3	GND	Power ground
4	R0	Red data (LSB)
5	R1	Red data
6	R2	Red data
7	R3	Red data
8	R4	Red data
9	R5	Red data
10	R6	Red data
11	R7	Red data (MSB)
12	G0	Green data (LSB)
13	G1	Green data
14	G2	Green data
15	G3	Green data
16	G4	Green data
17	G5	Green data
18	G6	Green data
19	G7	Green data (MSB)
20	B0	Blue data (LSB)
21	B1	Blue data
22	B2	Blue data
23	B3	Blue data
24	B4	Blue data
25	B5	Blue data
26	B6	Blue data
27	B7	Blue data (MSB)
28	GND	Power ground
29	DISP	Display on/ off
30	GND	Power ground
31	HSYN	Horizontal sync signal
32	VSYNC	Vertical sync signal
33	DE	Data enable
34	NC	No connect
35	NC	No connect
36	GND	Power ground
37	XR	Bottom electrode – differential analog
38	YD	Bottom electrode – differential analog
39	XL	Left electrode – differential analog
40	YU	Top electrode – differential analog

■ CTP OUTLINE DRAWING



■ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Supply voltage for logic	VDD	-0.3	4.0	V
Input voltage for logic	VIN	-0.5	VDD+0.3	V
Supply current(One LED)	I_{LED}	-	30	mA
Operatingtemperature	Top	-20	70	°C
Storagetemperature	TST	-30	80	°C
Humidity	RH	-	90%(Max60 °C)	RH

■ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage for logic	VDD	3.0	3.3	3.6	V
Inputvoltage'H'level	VIH	0.8VDD	-	VDD	V
Inputvoltage'L'level	VIL	-0.3	-	0.3VDD	V
Input leakage current	I_{LKG}	-	-	-	μA
LED forward voltage	Vf	3.0	3.2	3.4	V
Input backlight current(one LED)	I_{LED}	-	20	25	mA
LED life time	LED	-	TBD	-	Hr

■ELECTRO-OPTICAL CHARACTERISTICS

Item	Symbol	Condition	Min	Typ	Max	Unit	Remark	Note
Response time	Tr +Tf	θ=0° ∅=0° Ta=25℃	-	50	70	ms	Fig.1	4
Contrastratio	Cr		400	500	-	---	FIG 2.	1
Luminance uniformity	δ WHITE		75	80	-	%	FIG 2.	3
Surface Luminance	Lv		310	350	-	cd/m^2	FIG 2.	2
Viewing angle range	θ	∅ = 90°	60	70	-	deg	FIG 3.	6
		∅ = 270°	40	50	-	deg	FIG 3.	
		∅ = 0°	60	70	-	deg	FIG 3.	
		∅ = 180°	60	70	-	deg	FIG 3.	
CIE (x, y) chromaticity	Red x	θ=0° ∅=0° Ta=25℃	-	0.581	-		FIG 2.	5
	Red y		-	0.345	-			
	Green x		-	0.348	-			
	Green y		-	0.581	-			
	Blue x		-	0.153	-			
	Blue y		-	0.095	-			
	White x		-	0.315	-			
	White y		-	0.335	-			

Note 1. Contrast Ratio(CR) is defined mathematically as For more information see FIG 2.:

$$\textbf{Contrast Ratio} = \frac{\text{Average Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}{\text{Average Surface Luminance with all black pixels } (P_1, P_2, P_3, P_4, P_5)}$$

Note 2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv = Average Surface Luminance with all white pixels $(P_1, P_2, P_3, P_4, P_5)$

Note 3. The uniformity in surface luminance , δ WHITE is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

$$\delta\ \textbf{WHITE} = \frac{\textbf{Minimum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}{\textbf{Maximum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}$$

Note 4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1. The test equipment is Autronic-Melchers's ConoScope. Series

Note 5. CIE (x, y) chromaticity,The x,y value is determined by measuring luminance at each test position 1 through 5,and then make average value

Note 6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the conrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note 7. For Viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments. For contrast ratio, Surface Luminance, Luminance uniformity,CIE The test data is base on TOPCON's BM-5 photo detector.

Note 8. For TFT module, Gray scale reverse occurs in the direction of panel viewing angle.

FIG.1. The definition of Response Time

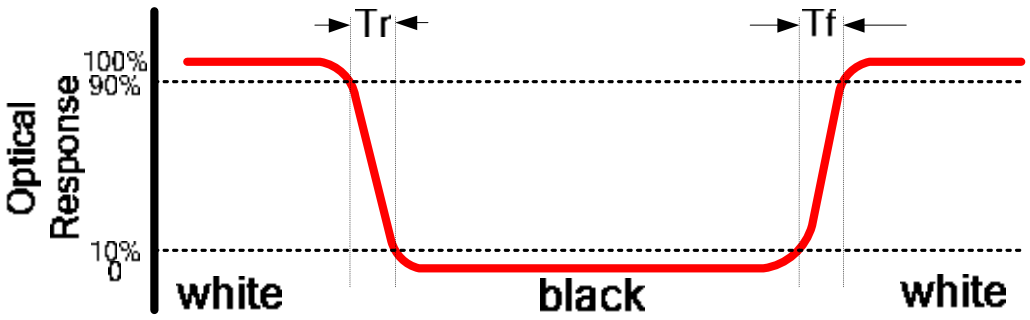


FIG.2. Measuring method for Contrast ratio,surface luminance, Luminance uniformity , CIE (x, y) chromaticity

A : 5 mm
B : 5 mm
H,V : Active Area
Light spot size ∅=5mm, 500mm distance from the LCD surface to detector lens
measurement instrument is TOPCON's luminance meter BM-5

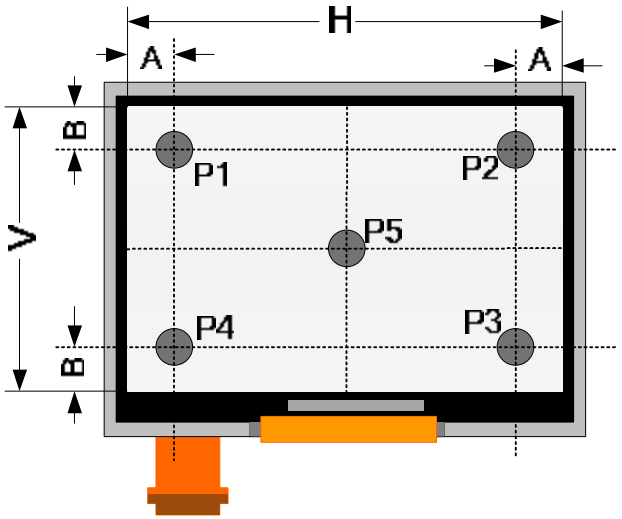
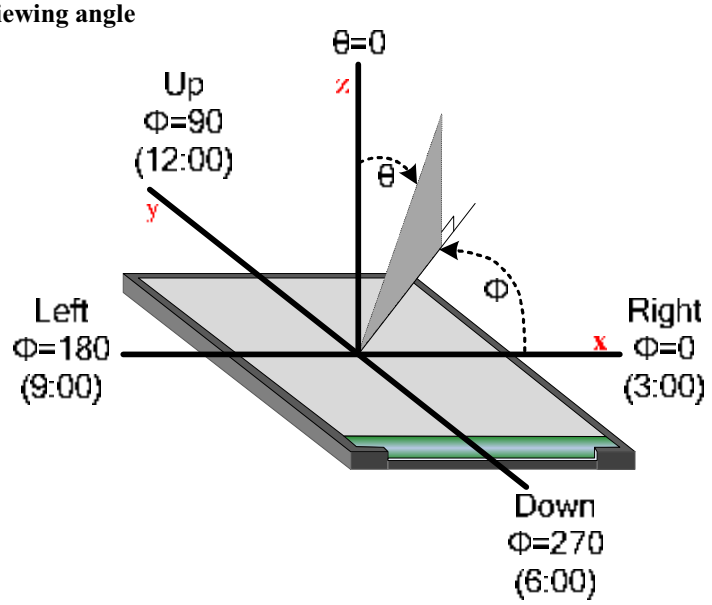


FIG.3. The definition of viewing angle



■ INTERFACE DESCRIPTION

Pin No.	Symbol	Description
1	VLED-	Cathode of LED backlight
2	VLED+	Anode of LED backlight
3	GND	Power ground
4	VDD	Power voltage
5	R0	Red data (LSB)
6	R1	Red data
7	R2	Red data
8	R3	Red data
9	R4	Red data
10	R5	Red data
11	R6	Red data
12	R7	Red data (MSB)
13	G0	Green data (LSB)
14	G1	Green data
15	G2	Green data
16	G3	Green data
17	G4	Green data
18	G5	Green data
19	G6	Green data
20	G7	Green data(MSB)
21	B0	Blue data(LSB)
22	B1	Blue data
23	B2	Blue data
24	B3	Blue data
25	B4	Blue data
26	B5	Blue data
27	B6	Blue data
28	B7	Blue data(MSB)
29	GND	Power ground
30	DCLK	Pixel clock
31	DISP	Display on/off
32	HSYN	Horizontal sync signal
33	VSYNC	Vertical sync signal
34	DE	Data enable
35	NC	NO connect
36	GND	Power ground
37	NC	NO connect
38	NC	NO connect
39	NC	NO connect
40	NC	NO connect

■ TOUCH SCREEN PANEL SPECIFICATIONS

1. GENERAL SPECIFICATIONS

Item	Specification	Unit
Type	Transparent type projected capacitive touch panel	
Input mode	Human's finger	
Substrate Thickness	0.55	mm
Outline Dimension	115.1(W) x 73.9(H)*1.4(D)	mm
Transparency	≧85	%
Haze	≦1.0	%

2. ELECTRICAL CHARACTERISTICS

2.1 Absolute Maximum Ratings

Parameter	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
Supply voltage	VCC	-0.3	-	7	V
Switch control signals output current	Output current	-	50	-	mA
Enable control voltage range	Logic Input	-0.3	-	VCC+0.3	V
Output Control Driver	Output voltage	-0.3	-	VCC	V
Operating temperature	Temperature OP	-20	--	60	°C
Storage temperature	Temperature ST	-30	--	70	°C

2.2 DC characteristics

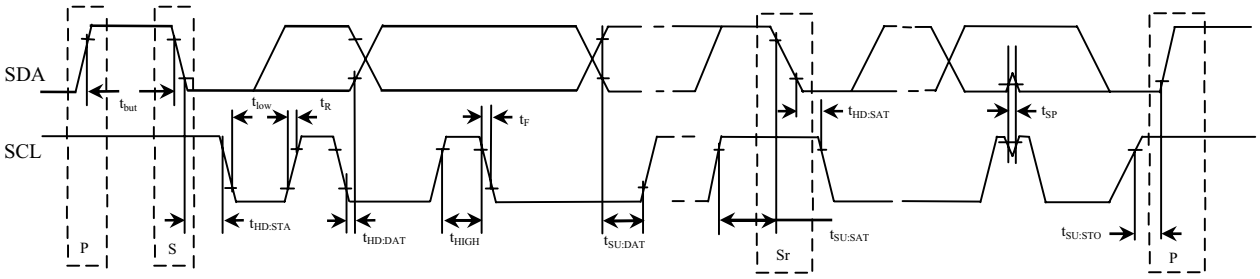
Parameter	Symbol	Spec.			Unit
		Min.	Typ.	Max.	
Supply voltage	VCC	2.7	3.3	3.5	
Input high voltage	V_{IH}	0.7 * VCC	-	VCC	V
Input low voltage	V_{IL}	0	-	0.3 *VCC	V

3. PIN CONNECTIONS

No.	Name	I/O	Description
1	GND	-	Ground
2	GND	-	Ground
3	XRES	I	NC pin; please keep floating
4	XRES	I	NC pin; please keep floating
5	INT	O	Interrupt, Active low
6	INT	O	Interrupt, Active low
7	SCL	I	Serial Clock access
8	SCL	I	Serial Clock access
9	SDA	I/O	Serial data access
10	SDA	I/O	Serial data access
11	VCC	-	Power; VCC=+3.3V

12	VCC	-	Power; VCC=+3.3V

4. TIMING CHARACTERISTICS



Parameter	Symbol	Standard-Mode I²C-BUS		Fast-Mode I²C-BUS		Unit
		Min.	Max.	Min.	Max.	
SCL clock frequency	f_{SCL}	0	100	0	400	KHz
Bus free time between STOP and START condition	t_{BUF}	4.7	-	1.3	-	μs
Hold time (repeated) START condition. After this period, the first clock pulse is generated	$t_{HD:STA}$	4.0	-	0.6	-	μs
LOW period of the SCL clock	t_{LOW}	4.7	-	1.3	-	μs
HIGH period of the SCL clock	t_{HIGH}	4.0	-	0.6	-	μs
Set-up time for a repeated START condition	$t_{SU:STA}$	4.7	-	0.6	-	μs
Data hold time	$t_{HD:DAT}$	0	-	0	0.9	μs
Data set-up time	$t_{SU:DAT}$	250	-	100	-	μs
Rise time of both SDA and SCL signals	t_R	-	1000	$20+0.1C_b$	300	μs
Fall time of both SDA and SCL signals	t_F	-	300	$20+0.1C_b$	300	μs
Set-up time for STOP condition	$t_{SU:STO}$	4.0	-	0.6	-	μs
Capacitive load for each bus line.	C_b	-	400	-	400	pF

Note:

(1) All values are referred to VIH (0.7xVCC) and VIL (0.3xVCC) level.

(2) A device must internally provide a hold time of at least 300ns for the SDA signal (referred to the VIH of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

(3) The maximum $t_{HD:DAT}$ has only to be met if the device does not stretch the LOW period (t_{LOW}) of the SCL signal.

(4) A fast-mode I²C-bus device can be used in a standard-mode I²C-bus system, but the requirement $t_{SU:DAT} \geqq 250ns$ must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line $t_{R\,max}$ $t_{SU:DAT}$ = 1000+250=1250ns (according to the standard-mode I²C-bus specification) before the SCL line is released.

(5) C_b = total capacitance of one bus line in pF.

(6) If a spark or noise appear on SDA line and keep more than 25ns, Start or Stop condition will be identified if SCL
line keep high at this time.

5. Interface and Data Format

5.1 Transfer protocol (I²Cinterface)

MI0430CCP-C support I²C interface that need 2 hardware pin – serial data (SDA) and serial clock (SCL), carry information between the devices connected to the bus. The I²C bus supports serial, 8-bit oriented, bi-directional data transferred at a rate up to 100Kbit/s in the standard-mode, or up to 400Kbit/s in the fast-mode.

The data on the SDA line must be stable during the HIGH period of the clock. The HIGH or LOW state of the data line can only change when the clock signal on the SCL line is LOW.

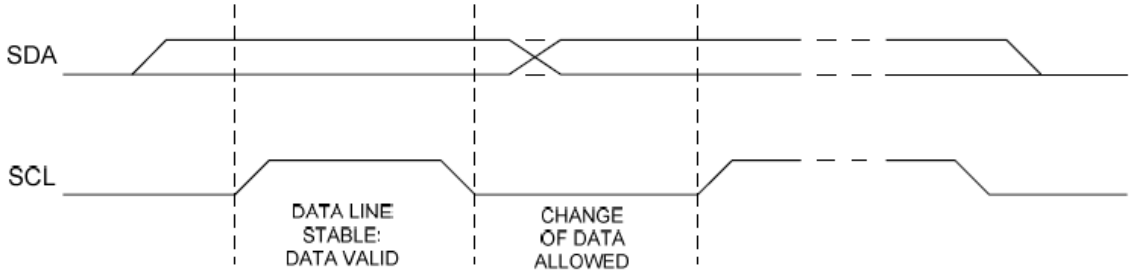


Figure 7.1: I²C Signal timing

Within the procedure of the I²C -bus, unique situations arise which are defined as START and STOP conditions. A HIGH to LOW transition on the SDA line while SCL is HIGH is one such unique case. This situation indicates a START condition. A LOW to HIGH transition on the SDA line while SCL is HIGH defines a STOP condition. START and STOP conditions are always generated by the master. The I²C bus is considered to be busy after the START condition. The I²C bus is considered to be free again a certain time after the STOP condition.

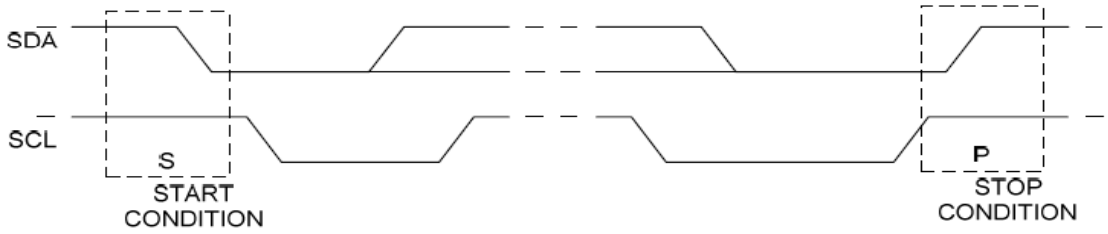


Figure 7.2: I²C Start/Stop

5.2 I²C data transfer

The CTP MI0430CCP-C I²C address is**0x90H**

Each byte has to be followed by an acknowledge bit. Data is transferred with the most significant bit (MSB) first. Every byte put on the SDA line must be 8-bits long. The number of bytes that can be transmitted per transfer is unrestricted. If controller can't receive or transmit another complete byte of data until it has performed some other function, for example servicing an internal interrupt, it can hold the clock line SCL LOW to force the master into await state. Data transfer then continues when the controller is ready for another byte of data and releases clock line SCL.

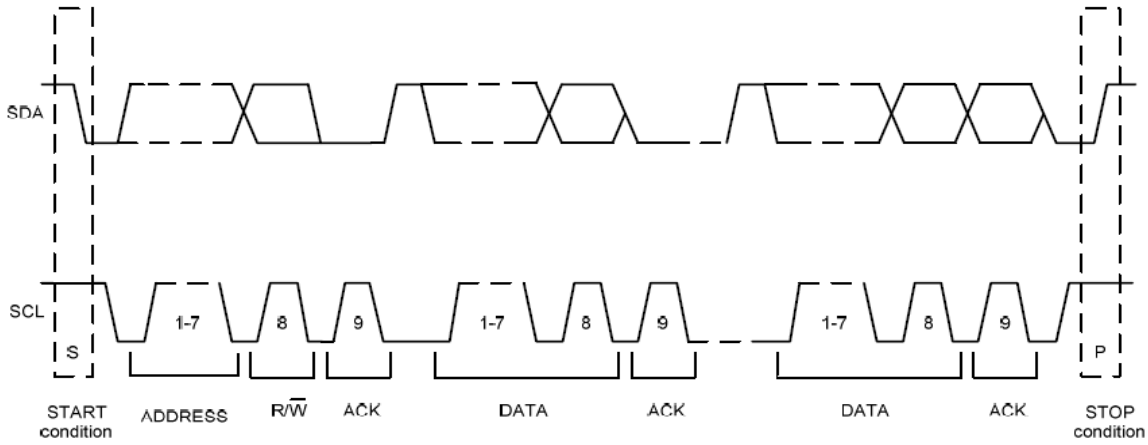


Figure 7.3: I²C data transfer

5.3 Format of data frame (I²C interface)

When master sends the command which be received by TP controller, the controller will responses the code and data. The format of communication is shown as Figure 7.4. The Command table that is written by master is defined on Command Table, Controller will response the response code first and data later.

Write mode

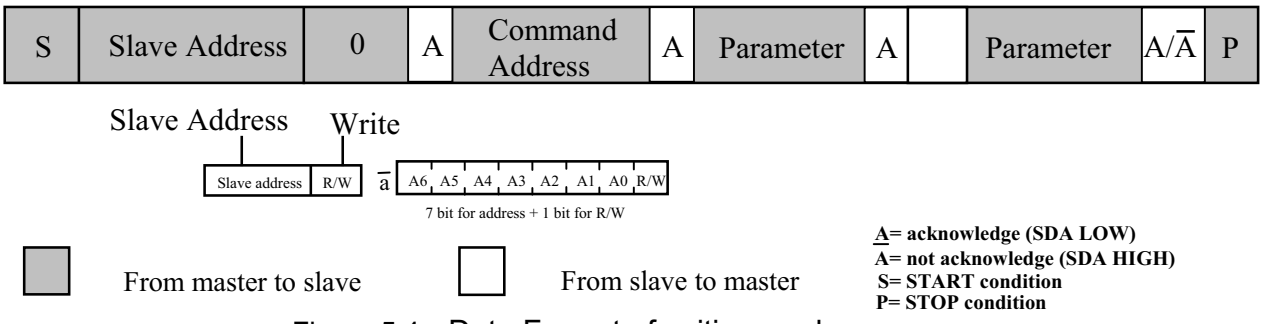


Figure 5.4 Data Format of writing mode

Read mode

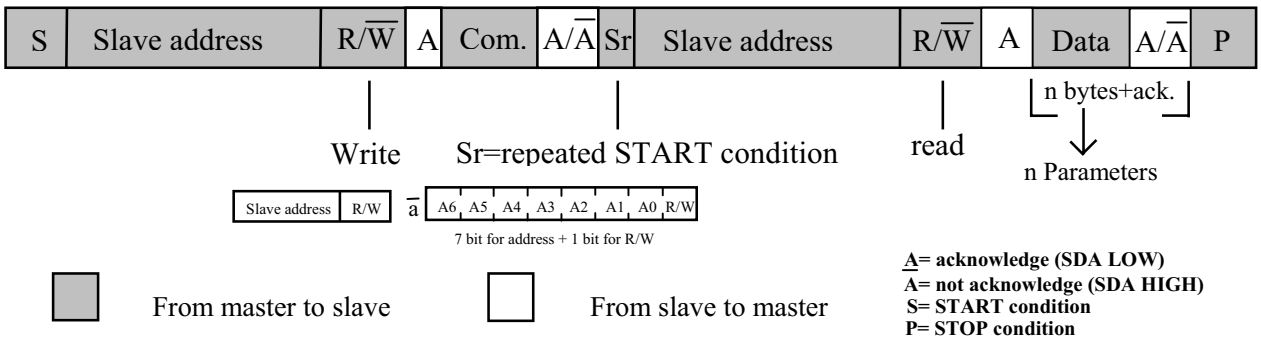


Figure 5.4 Data Format of reading mode

6. Command

6.1 Command list

Hex	Operation Code	D7	D6	D5	D4	D3	D2	D1	D0	Function
0	No operation	0	0	0	0	0	0	0	0	-
80	Sleep IN	1	0	0	0	0	0	0	0	-
81	Sleep Out	1	0	0	0	0	0	0	1	-
82	Sense Off	1	0	0	0	0	0	1	0	-
83	Sense On	1	0	0	0	0	0	1	1	-
85	Read Event	1	0	0	0	0	1	0	1	-
	1st parameter	B31	B30	B29	B28	B27	B26	B25	B24	-
	2nd parameter	B23	B22	B21	B20	B19	B18	B17	B16	-
	3rd parameter	B15	B14	B13	B12	B11	B10	B9	B8	-
	4th parameter	B7	B6	B5	B4	B3	B2	B1	B0	-
86	Read All Events	1	0	0	0	0	1	1	0	-
	1st parameter	B31	B30	B29	B28	B27	B26	B25	B24	-
	2nd parameter	B23	B22	B21	B20	B19	B18	B17	B16	-
	3rd parameter	B15	B14	B13	B12	B11	B10	B9	B8	-
	4th parameter	B7	B6	B5	B4	B3	B2	B1	B0	-
	5th parameter	E3	E2	E1	E0	FI	P2	P1	P0	-
	6th parameter	B23	B22	B21	B20	B19	B18	B17	B16	-
	…	:	:	:	:	:	:	:	:	-
	(n+1)th parameter	B7	B6	B5	B4	B3	B2	B1	B0	-
87	Read Latest Event	1	0	0	0	0	1	1	1	-
	1st parameter	B31	B30	B29	B28	B27	B26	B25	B24	-
	2nd parameter	B23	B22	B21	B20	B19	B18	B17	B16	-
	3rd parameter	B15	B14	B13	B12	B11	B10	B9	B8	-
	4th parameter	B7	B6	B5	B4	B3	B2	B1	B0	-
88	Clear Stack	1	0	0	0	1	0	0	0	-
9E	TS Software Reset	1	0	0	1	1	1	1	0	-

6.2 User define command list table

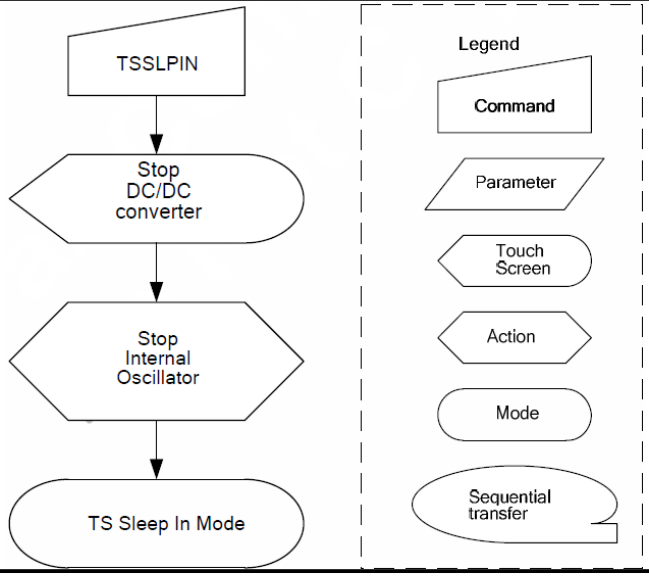
Hex	Operation Code	D7	D6	D5	D4	D3	D2	D1	D0	Function
31h	Device ID	0	0	1	1	0	0	0	1	Response Device ID Code
	1st parameter	85								-
	2nd parameter	20								-
	3nd parameter	00								-
32h	Version ID	0	0	1	1	0	0	0	1	Read Firmware version

7. Command description

7.1 NOP

<table>
<tr><td>00 H</td><td colspan="10">NOP (No Operation)</td></tr>
<tr><td></td><td>DNC</td><td>D7</td><td>D6</td><td>D5</td><td>D4</td><td>D3</td><td>D2</td><td>D1</td><td>D0</td><td>HEX</td></tr>
<tr><td>Command</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>00</td></tr>
<tr><td>Parameter</td><td colspan="10">No parameter</td></tr>
<tr><td>Description</td><td colspan="10">This command is an empty command and it does not have any effect on the touch screen.</td></tr>
<tr><td>Restriction</td><td colspan="10"></td></tr>
<tr><td>Register Availability</td><td colspan="10"><table><tr><td>Status</td><td>Availability</td></tr><tr><td>TS Sleep Out</td><td>Yes</td></tr><tr><td>TS Sleep In</td><td>Yes</td></tr></table></td></tr>
<tr><td>Default</td><td colspan="10"><table><tr><td>Status</td><td>Default Value</td></tr><tr><td>Power Up Sequence</td><td>N/A</td></tr><tr><td>TS S/W Reset</td><td>N/A</td></tr><tr><td>H/W Reset</td><td>N/A</td></tr></table></td></tr>
<tr><td>Flow Chart</td><td colspan="10"></td></tr>
</table>

7.2 TS sleep in (80h)

<table>
<tr><td rowspan="2">80H</td><td colspan="10">TSSLPIN (Touch Screen Sleep In)</td></tr>
<tr><td>DNC</td><td>D7</td><td>D6</td><td>D5</td><td>D4</td><td>D3</td><td>D2</td><td>D1</td><td>D0</td><td>HEX</td></tr>
<tr><td>Command</td><td>0</td><td>1</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>80</td></tr>
<tr><td>parameter</td><td colspan="10">No parameter</td></tr>
<tr><td>Description</td><td colspan="10">This command causes the touch screen to enter the minimum power consumption mode.
MCU interface are register are still working and keeps their contents.</td></tr>
<tr><td>Restriction</td><td colspan="10">This command has no effect when the touch screen is already in TS Sleep In mode. TS Sleep In Mode can only be left by the TS Sleep Out Command (81h).
It will be necessary to wait 5msec before sending next command. This is to allow time for the supply voltages and clock circuits to stabilize.
It will be necessary to wait 5msec after sending TS Sleep Out command (when in TS Sleep In Mode) before TS Sleep In command can be sent.</td></tr>
<tr><td>Register Availability</td><td colspan="10"><table><tr><td>Status</td><td>Availability</td></tr><tr><td>TS Sleep Out</td><td>Yes</td></tr><tr><td>TS Sleep In</td><td>Yes</td></tr></table></td></tr>
<tr><td>Default</td><td colspan="10"><table><tr><td>Status</td><td>Default Value</td></tr><tr><td>Power Up Sequence</td><td>TS Sleep In Mode</td></tr><tr><td>TS S/W Reset</td><td>TS Sleep In Mode</td></tr><tr><td>H/W Reset</td><td>TS Sleep In Mode</td></tr></table></td></tr>
<tr><td>Flow Chart</td><td colspan="10"> 
</td></tr>
</table>

7.3 TS sleep out (81h)

81H	**TSSLPOUT** (Touch Screen Sleep Out)									
	DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command	0	1	0	0	0	0	0	0	1	81
parameter	No parameter									
Description	This command turns off TS Sleep In mode.									
Restriction	This command has no effect when touch screen is already in TS Sleep Out mode. TS Sleep Out Mode can only be left by the TS Sleep In Command (80h). It will be necessary to wait 5msec before sending next command. This is to allow time for the supply voltages and clock circuits to stabilize. The touch screen loads all touch screen supplier's factory default values to the registers during this 5msec and there cannot be any abnormal effect on the touch screen functionality if factory default and register values are same when this load is done and when the touch screen is already TS Sleep Out – mode. It will be necessary to wait 5msec after sending TS Sleep In command (when in TS Sleep Out mode) before TS Sleep Out command can be sent.									

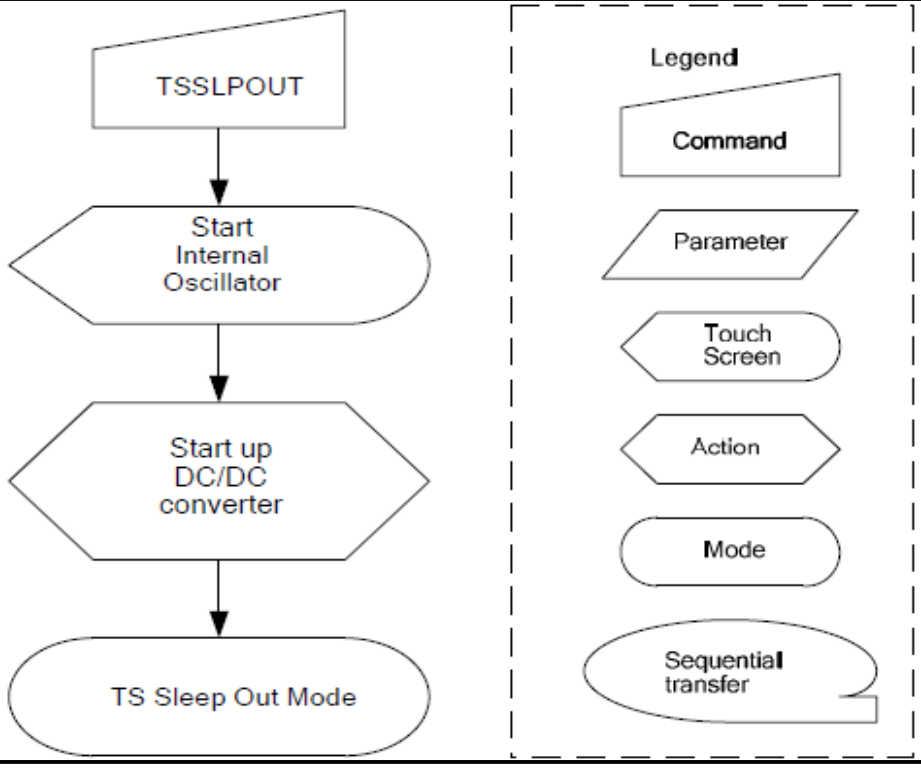
Register Availability

Status	Availability
TS Sleep Out	Yes
TS Sleep In	Yes

Default

Status	Default Value
Power Up Sequence	TS Sleep In Mode
TS S/W Reset	TS Sleep In Mode
H/W Reset	TS Sleep In Mode

Flow Chart



7.4 TS sense off (82h)

82H	**TSSOFF** (Touch Screen Sense Off)									
	DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command	0	1	0	0	0	0	0	1	0	82
parameter	No parameter									
Description	The touch screen is not sensing touches (= No new events), but the touch screen is still scanning.									
Restriction										

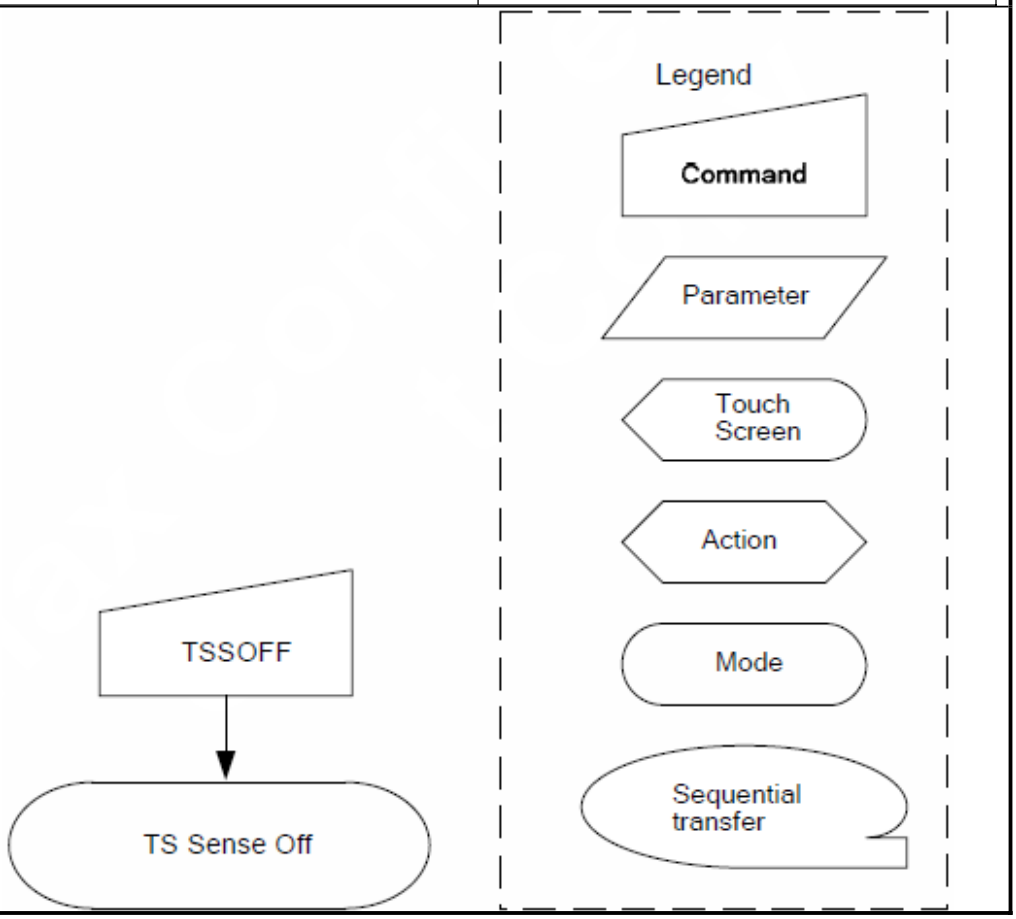
Register Availability

Status	Availability
TS Sleep Out	Yes
TS Sleep In	Yes

Default

Status	Default Value
Power Up Sequence	TS Sense Off
TS S/W Reset	TS Sense Off
H/W Reset	TS Sense Off

Flow Chart



7.5 TS sense on (83h)

83H	**TSSON** (Touch Screen Sense On)									
	DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command	0	1	0	0	0	0	0	1	1	83
parameter	No parameter									
Description	The touch screen is sensing touches (= No new events).									
Restriction										

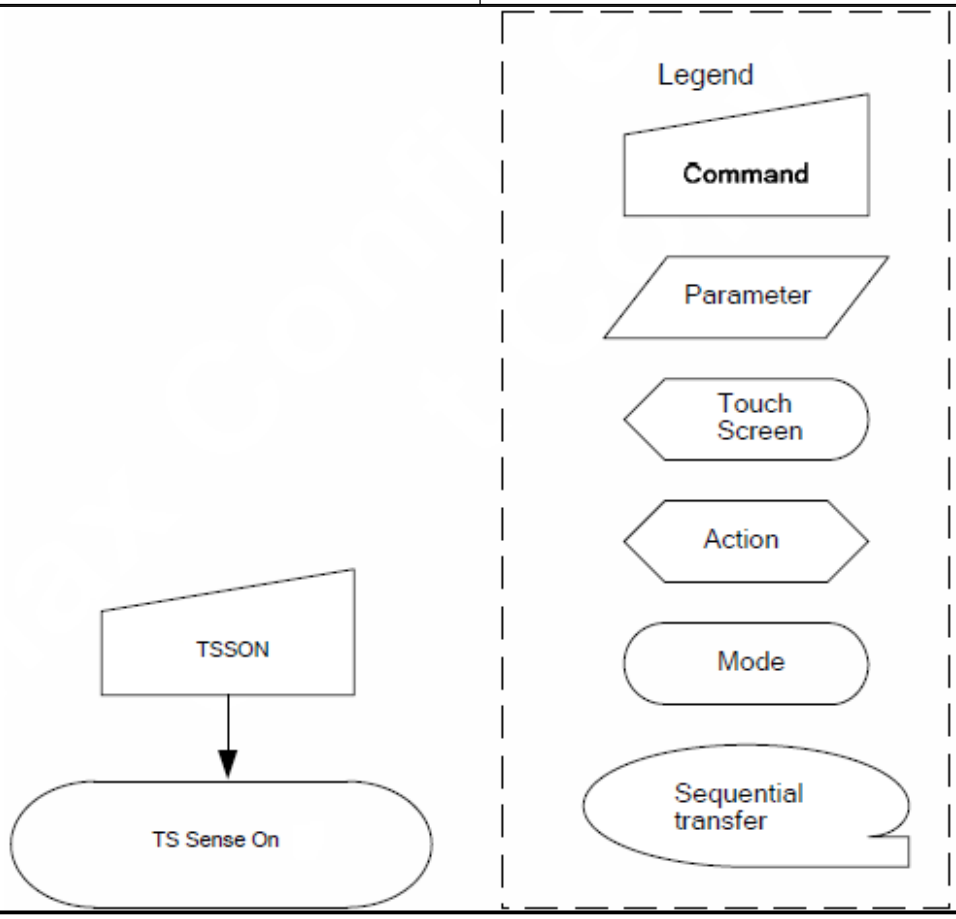
Register Availability

Status	Availability
TS Sleep Out	Yes
TS Sleep In	Yes

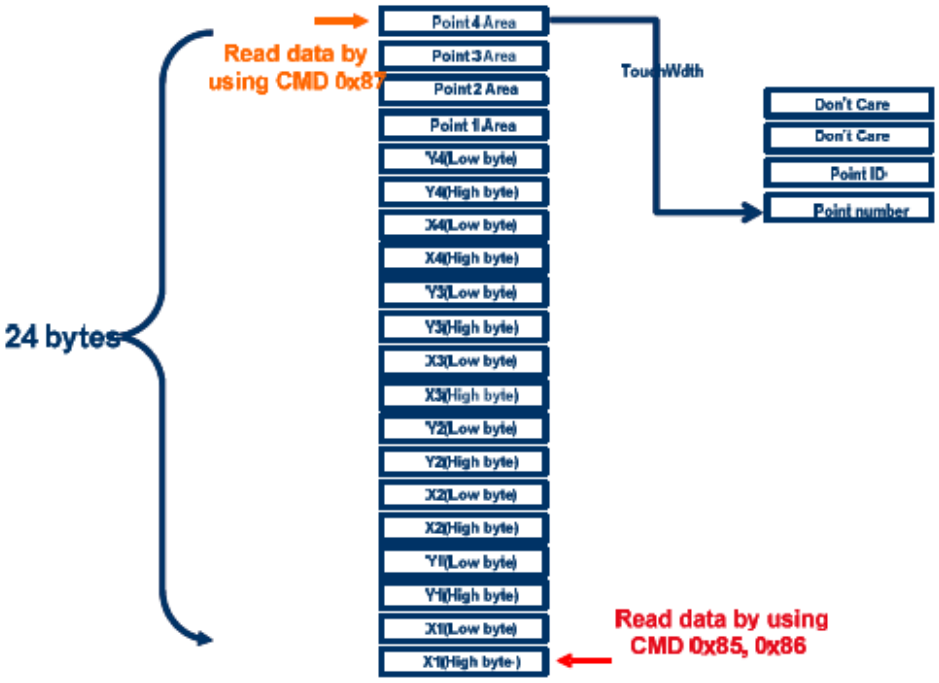
Default

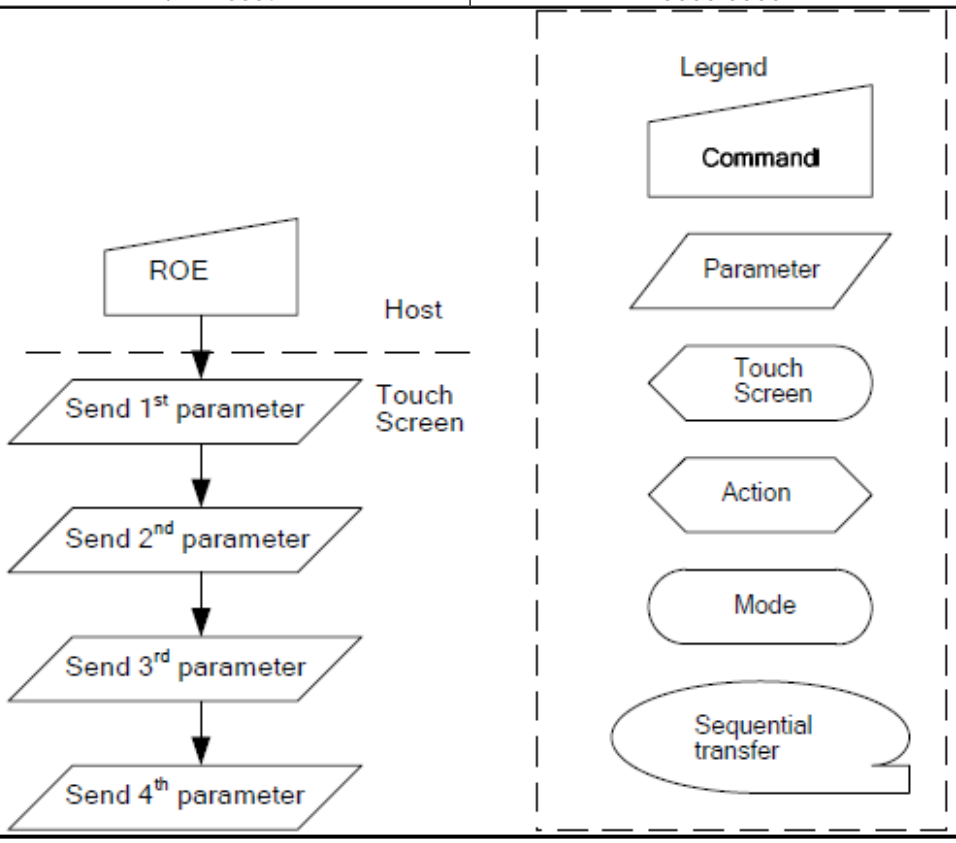
Status	Default Value
Power Up Sequence	TS Sense Off
TS S/W Reset	TS Sense Off
H/W Reset	TS Sense Off

Flow Chart



7.6 Read One Event (85h)

85H		ROE (Read One Event)									
		DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command		0	1	0	0	0	0	1	0	1	85
1	parameter	-	B31	B30	B29	B28	B27	B26	B25	B24	xx
2	parameter	-	B23	B22	B21	B20	B19	B18	B17	B16	xx
3	parameter	-	B15	B14	B13	B12	B11	B10	B9	B8	xx
4	parameter	-	B7	B6	B5	B4	B3	B2	B1	B0	xx
Description		This command returns one touch event what is the oldest co-ordinates or raw counter (dc) values information has been stored on the stock. The event stack is empty after this command. A returning value can be “No Event” if the stock is empty. co-ordinates and related touch information: Touch Width: Report the touched block. For example: if RX=15, TX=10, the total Block is 150 (96h). If it has three touched block, the report value is 03h. Point ID: Report the ID of touched points. Points number: Report the touch number.  When one or more points (but not all) have been touched, other points without touched will be fill invalid data 0xFFFF to let baseband distinguish which point has been touched or not.									

Register Availability	Status	Availability
	TS Sleep Out	Yes
	TS Sleep In	Yes
Default	Status	Default Value
	Power Up Sequence	0000 0000h
	TS S/W Reset	0000 0000h
	H/W Reset	0000 0000h
Flow Chart		

7.7 Read All Event (86h)

86H		RAE (Read All Events)									
		DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command		0	1	0	0	0	0	1	1	0	86
1	parameter	-	B31	B30	B29	B28	B27	B26	B25	B24	xx
2	parameter	-	B23	B22	B21	B20	B19	B18	B17	B16	xx
3	parameter	-	B15	B14	B13	B12	B11	B10	B9	B8	xx
4	parameter	-	B7	B6	B5	B4	B3	B2	B1	B0	xx
5	parameter	-	E3	E2	E1	E0	F1	P2	P1	P0	xx
6	parameter	-	B23	B22	B21	B20	B19	B18	B17	B16	xx
:		-	:	:	:	:	:	:	:	:	:
(n+1) Parameter		-	B7	B6	B5	B4	B3	B2	B1	B0	xx

Description

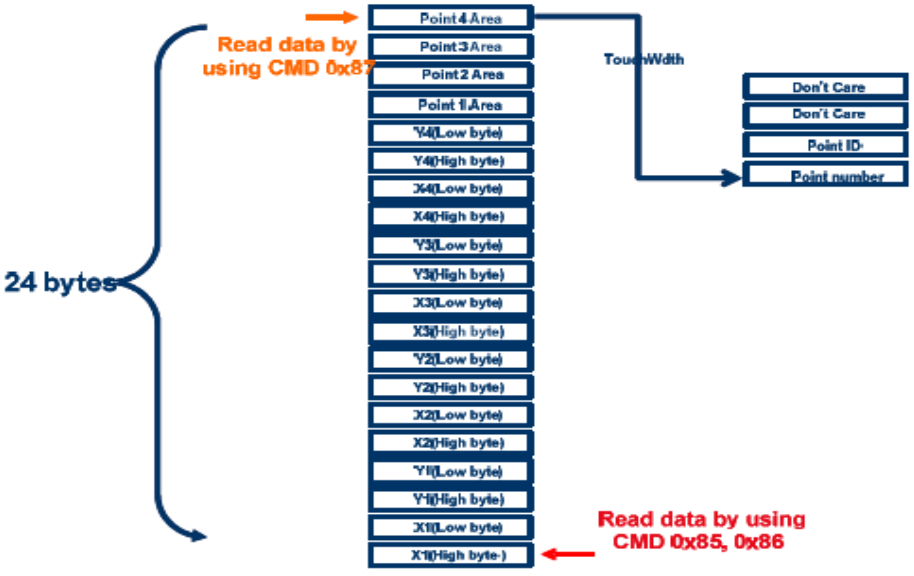
This command returns one touch event what is the oldest co-ordinates or raw counter (dc) values information has been stored on the stock. A returning value can be “No Event” if the stock is empty.

co-ordinates and related touch information:

Touch Width: Report the touched block. For example: if RX=15, TX=10, the total Block is 150 (96h). If it has three touched block, the report value is 03h.

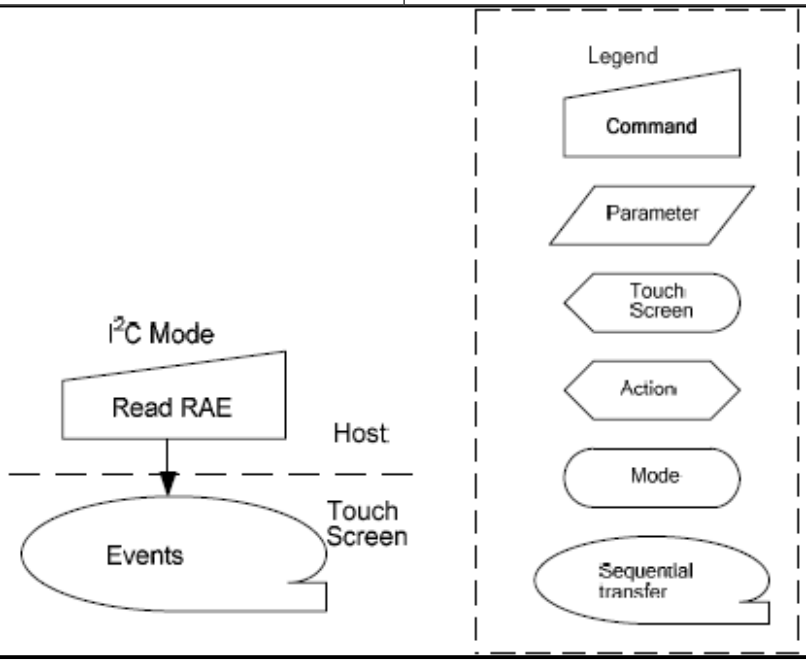
Point ID: Report the ID of touched points.

Points number: Report the touch number.

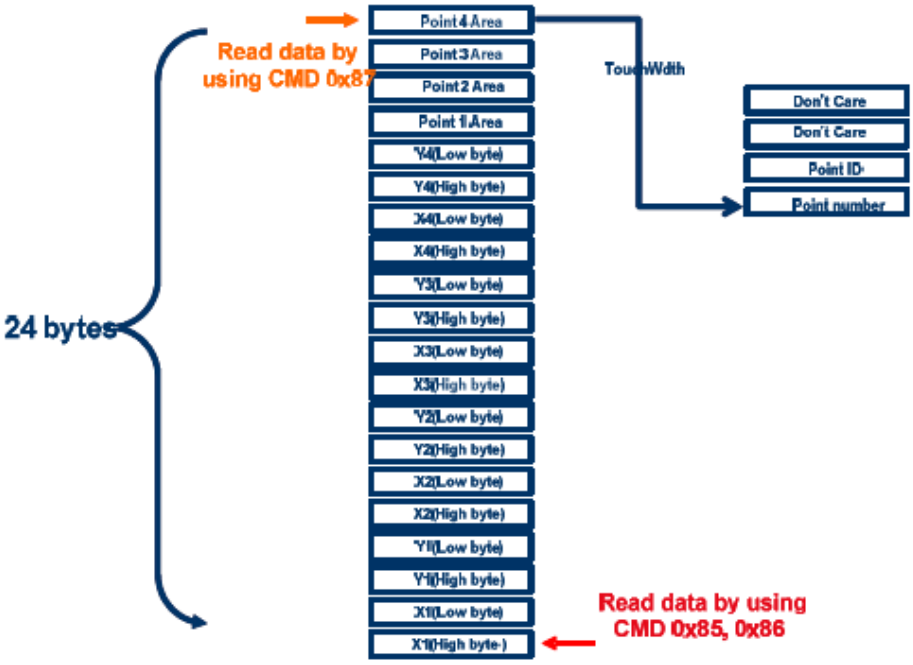


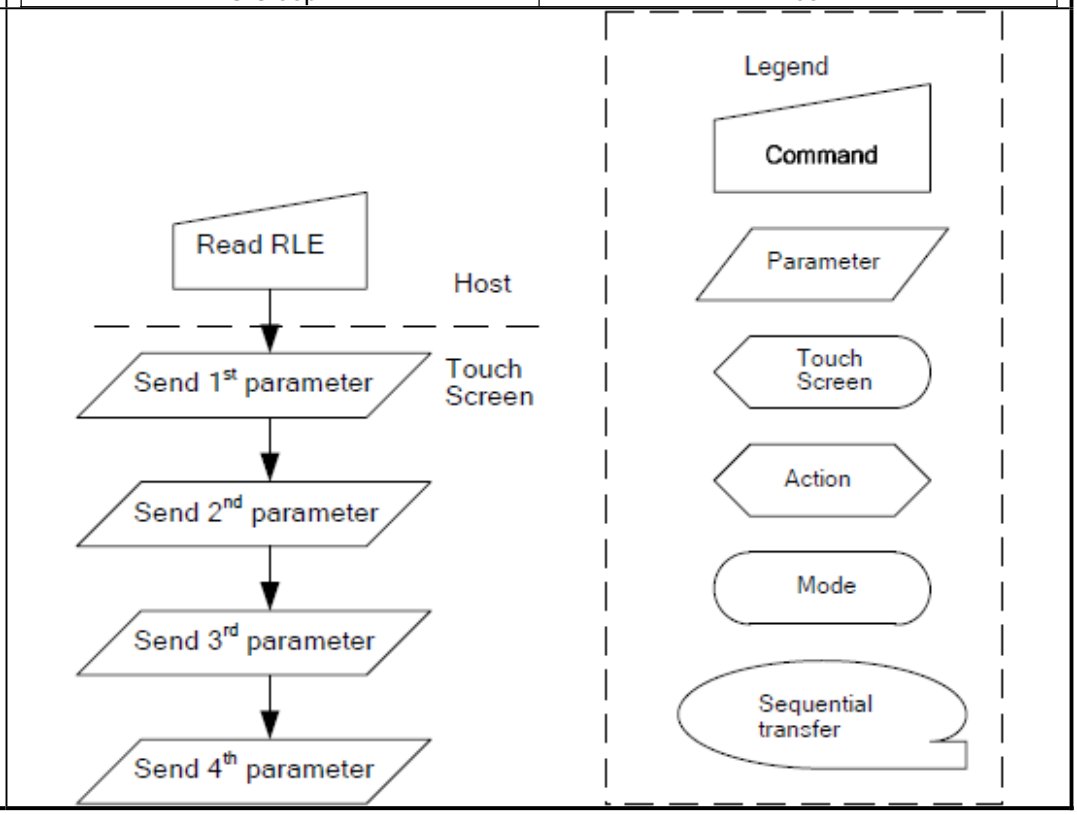
When one or more points (but not all) have been touched, other points without touched will be fill invalid data 0xFFFF to let baseband distinguish which point has been touched or not.

Register Availability	Status	Availability

	TS Sleep Out	Yes
	TS Sleep In	Yes
Default	Status	Default Value
	Power Up Sequence	All Values 0000 0000h
	TS S/W Reset	All Values 0000 0000h
Flow Chart		

7.8 Read Latest Event (87h)

87H		RLE (Read Latest Event)									
		DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command		0	1	0	0	0	0	1	1	1	87
1	parameter	-	B31	B30	B29	B28	B27	B26	B25	B24	xx
2	parameter	-	B23	B22	B21	B20	B19	B18	B17	B16	xx
3	parameter	-	B15	B14	B13	B12	B11	B10	B9	B8	xx
4	parameter	-	B7	B6	B5	B4	B3	B2	B1	B0	xx
Description		This command returns one touch event what is the oldest co-ordinates or raw counter (dc) values information has been stored on the stock. The event stack is empty after this command. A returning value can be “No Event” if the stock is empty. co-ordinates and related touch information: Touch Width: Report the touched block. For example: if RX=15, TX=10, the total Block is 150 (96h). If it has three touched block, the report value is 03h. Point ID: Report the ID of touched points. Points number: Report the touch number.  When one or more points (but not all) have been touched, other points without touched will be fill invalid data 0xFFFF to let baseband distinguish which point has been touched or not.									

Register Availability	Status	Availability
	TS Sleep Out	Yes
	TS Sleep In	Yes
Flow Chart		

7.9 Clear Event Stack (88h)

88H	**CLRES** (Clear Event Stack)									
	DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command	0	1	0	0	0	1	0	0	0	88
parameter	No parameter									
Description	This command clears event stack when the only return event can be “No Event”.									
Restriction										

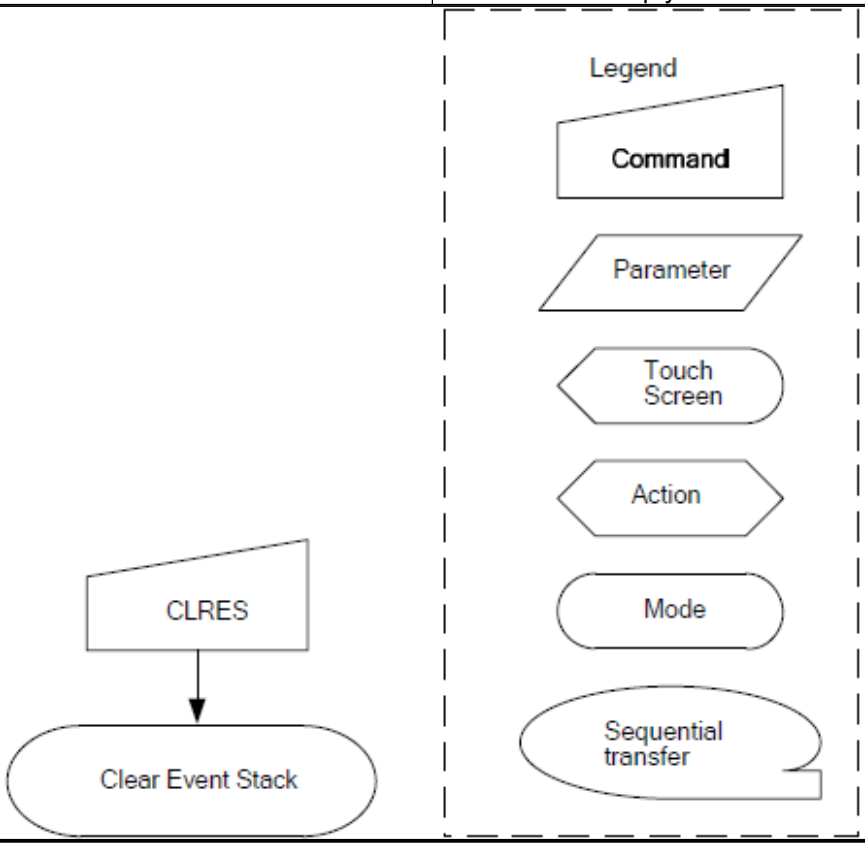
Register Availability

Status	Availability
TS Sleep Out	Yes
TS Sleep In	Yes

Default

Status	Default Value
Power Up Sequence	Empty Stack
TS S/W Reset	Empty Stack
H/W Reset	Empty Stack

Flow Chart



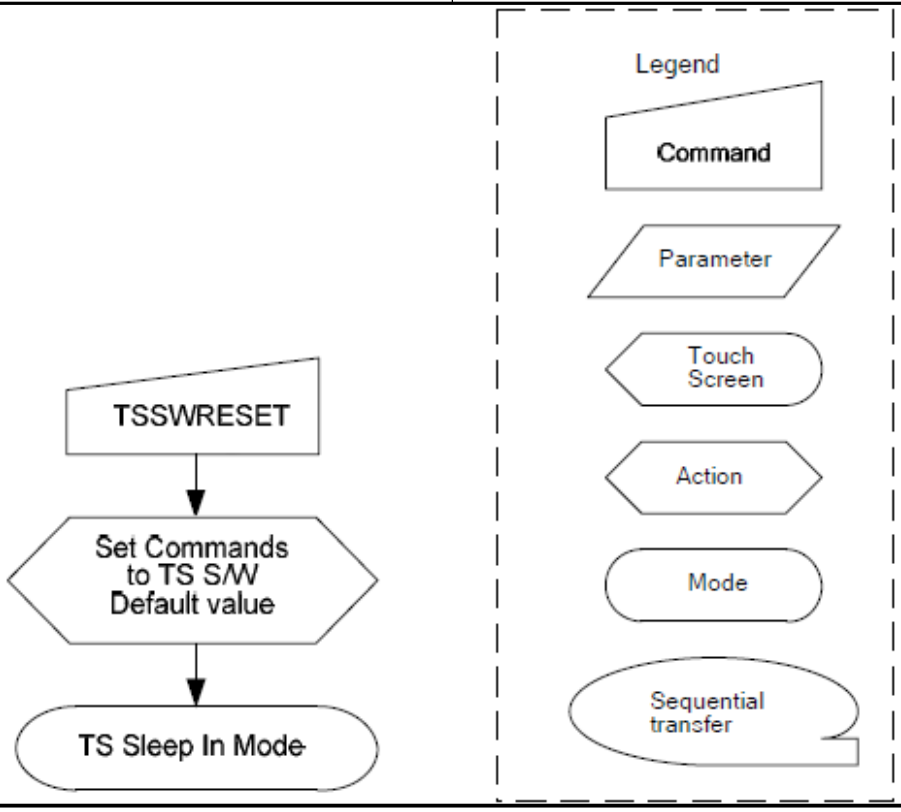
7.10 TS Software Reset (9Eh)

9E H	**TSSWRESET** (Touch Screen Software Reset)									
	DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command	0	1	0	0	1	1	1	1	0	9E
parameter	No parameter									
Description	When the Touch Screen Software Reset command is written, it causes a software reset. It resets the commands and parameters to their TS S/W Reset default values. (See default tables in each command description.) Note: The Memory contents are unaffected by this command									
Restriction	It will be necessary to wait 5msec before sending new command following software reset. The touch screen loads all touch screen supplier's factory default values to the registers during this 5msec. If Software Reset is applied during TS Sleep Out mode, it will be necessary to wait 5msec before sending TS Sleep Out command. Touch Screen Software Reset Command cannot be sent during TS Sleep Out sequence.									

Register Availability	Status	Availability
	TS Sleep Out	Yes
	TS Sleep In	Yes

Default	Status	Default Value
	Power Up Sequence	N/A
	TS S/W Reset	N/A
	H/W Reset	N/A

Flow Chart



7.11 Device ID Command (31h)

31 H	Device ID									
	DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command	0	0	0	1	1	0	0	0	1	31
1 parameter	1	85								00..FF
2 parameter	1	26								00..FF
3 parameter	1	00								00..FF
Description	When the Device ID command is written, IC will echo the device ID to master. The index of Device ID command is 31h									

Register Availability

Status	Availability
TS Sleep Out	Yes
TS Sleep In	Yes

Default

Status	Default Value
Power Up Sequence	N/A
TS S/W Reset	N/A
H/W Reset	N/A

Flow Chart

7.12 Version ID Command (32h)

32 H	Device ID									
	DNC	D7	D6	D5	D4	D3	D2	D1	D0	HEX
Command	0	0	0	1	1	0	0	1	0	31
1 parameter	1	SF_Version[3:0]				F_Version[3:0]				00..FF
Description	This command will report the ID code of firmware Version. F_Version [3:0]: The firmware version of flash code. SF_Version [3:0]: The firmware version of self test code.									

Register Availability

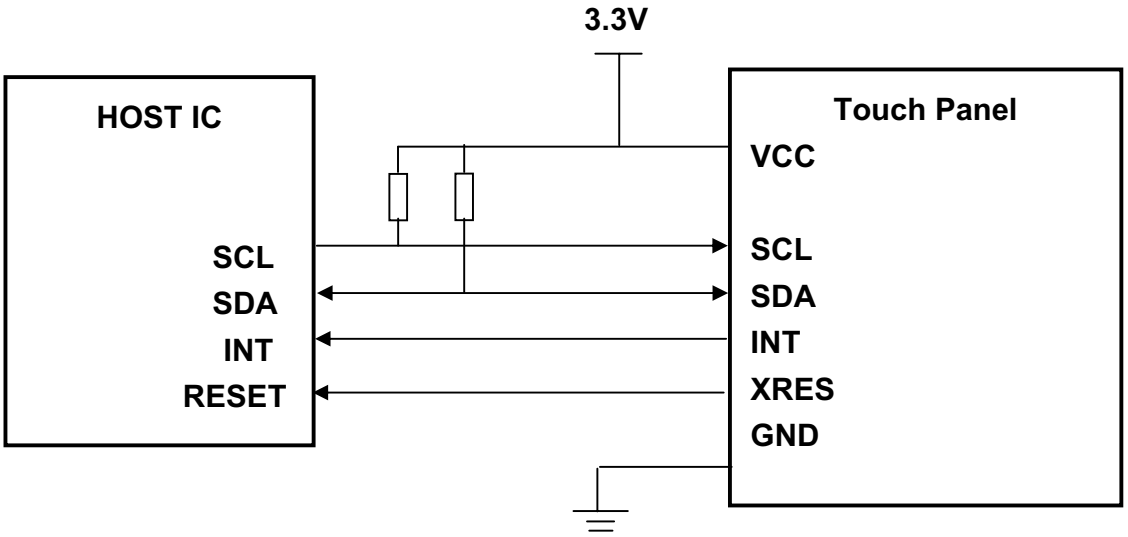
Status	Availability
TS Sleep Out	Yes
TS Sleep In	Yes

Default

Status	Default Value
Power Up Sequence	N/A
TS S/W Reset	N/A
H/W Reset	N/A

Flow Chart

8. BLOCK DIAGRAM



Note：1. USE APPROPRIATE RESISTOR VALUE DURING HIGH SPEED SCL CLOCK.

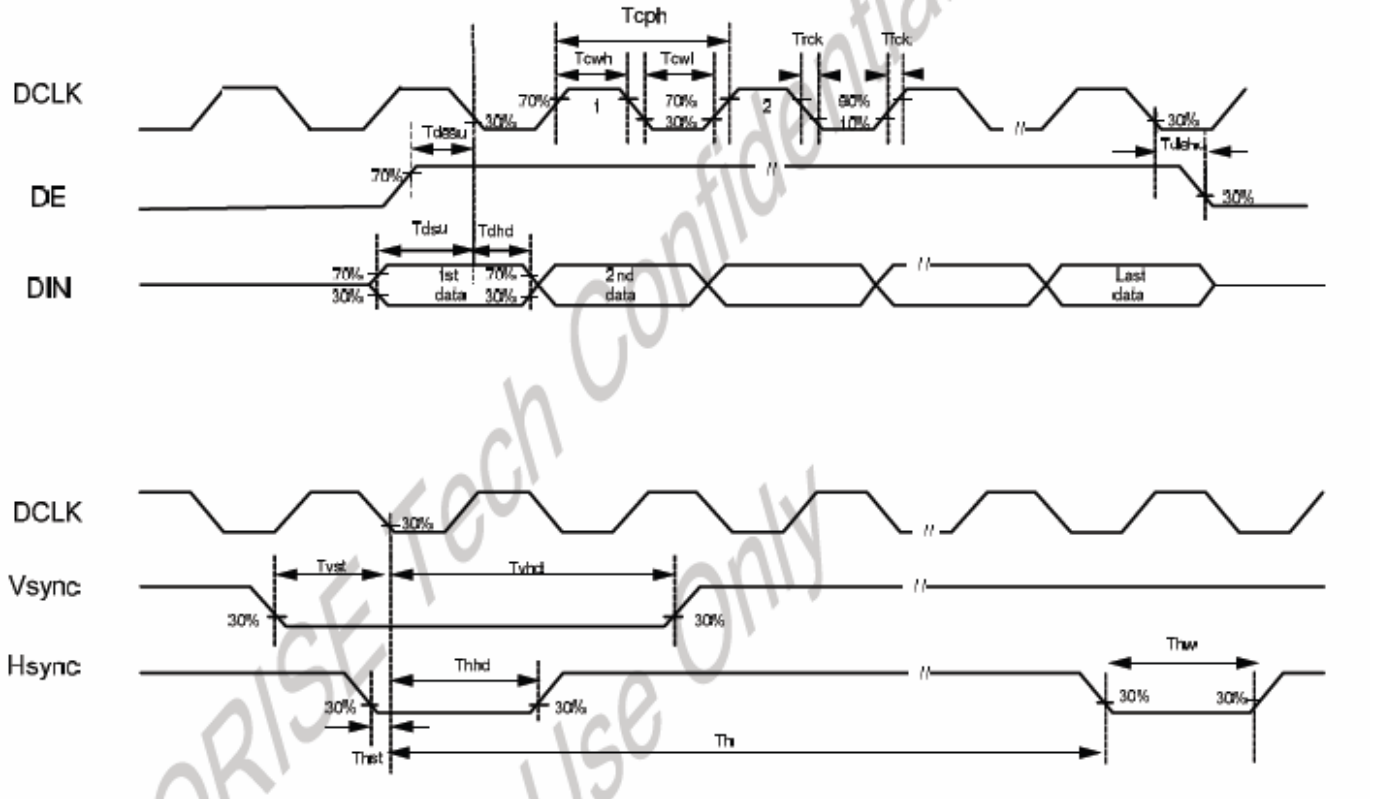
SUGGESTION : RESISTOR RECOMMENDATION：1K ohm.

2. To reduce the noise from the power, we suggest you use the independent power for the touch panel (VCC)

■ APPLICATION CIRCUIT NOTES

1. Timing/Characteristics

1.1 Clock and data input time diagram



1.2 Parallel RGB input timing table

Item		Symbol	Min.	Typ.	Max.	Unit	
DCLK Frequency		Fclk	5	9	12	MHz	
DCLK Period		Tclk	83	110	200	ns	
Hsync	Period Time	Th	490	531	605	DCLK	
	Display Period	Thdisp		480		DCLK	
	Back Porch	Thbp	8	43		DCLK	By H_BLANKING setting
	Front Porch	Thfp	2	8		DCLK	
	Pulse Width	Thw	1			DCLK	
Vsync	Period Time	Tv	275	288	335	H	
	Display Period	Tvdisp		272		H	
	Back Porch	Tvbp	2	12		H	By V_BLANKING setting
	Front Porch	Tvfp	1	4		H	
	Pulse Width	Tvw	1	10		H	

■ RELIABILITY TEST

No.	Test Item	Test Condition	Inspection after test
1	High Temperature Storage	80±2℃/240hours	1. Functional test is OK. Missing Segment, short, unclear segment, non-display, display abnormally and liquid crystal leak are un-allowed. 2. No low temperature bubbles, end seal loose and fall, frame rainbow.
2	Low Temperature Storage	-30±2℃/240hours	
3	High Temperature Operating	70±2℃/240hours	
4	Low Temperature Operating	-20±2℃/240hours	
5	Temperature Cycle	-30±2℃~25~80±2℃×10cycles (30min.) (5min.) (30min.)	
6	Damp Proof Test	40℃±5℃×90%RH/240hours	
7	Vibration Test	Frequency：10Hz~55Hz Amplitude：1.0mm, Each direction on X,Y axe 0.5 houre, circle 2 hours	1. Function test is OK. 2. No glass crack,chipped glass, end seal loose and fall, epoxy frame crack 3. No structure loose and fall.
8	Dropping test	Drop to the ground from 80cm height, one time, every side of carton.	

■ INSPECTION CRITERION

OUTGOING QUALITY STANDARD	PAGE 1 OF 7
TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA	

This specification is made to be used as the standard acceptance/rejection criteria for Color mobile phone LCM with touch panel.

1 Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1：1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

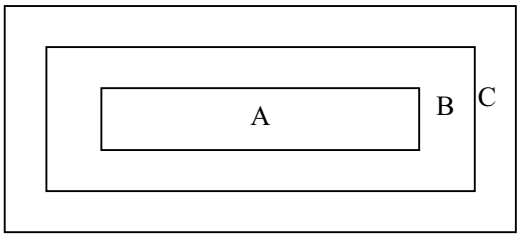
Major defect: AQL 0.65

Minor defect: AQL 1.5

2. Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45° against perpendicular line.

3. Definition of inspection zone in LCD.



Zone A: character/Digit area

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

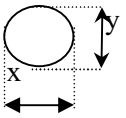
Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.

4. Inspection standards

4.1 Major Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects
4.1.1	All functional defects	1) No display 2) Display abnormally 3) Missing vertical， horizontal segment 4) Short circuit 5) Back-light no lighting, flickering and abnormal lighting.	Major
4.1.2	Missing	Missing component	
4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.	

4.2 Cosmetic Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects
4.2.1	Clear Spots Black and white Spot defect Pinhole, Foreign Particle, Dirt under polarizer	For dark/white spot, sizeΦis defined as $\Phi=\frac{(x+y)}{2}$ 	Minor
	Dim Spots Circle shaped and dim edged defects	2.	Minor

1.

Zone / Size(mm)	Acceptable Qty		
	A	B	C
Φ≤0.10	Ignore		Ignore
0.10＜Φ≤0.15	2		
0.15＜Φ≤0.20	1		
Φ＞0.20	0		

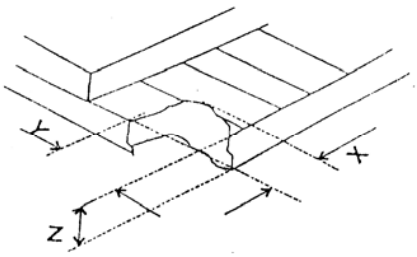
2.

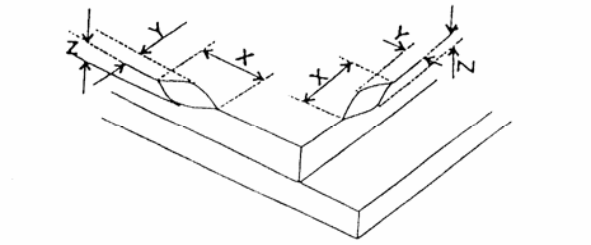
2. Zone / Size(mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		Ignore
0.20＜Φ≤0.40	3		
0.40＜Φ≤0.60	2		
0.60＜Φ≤0.80	1		
0.80＜Φ	0		

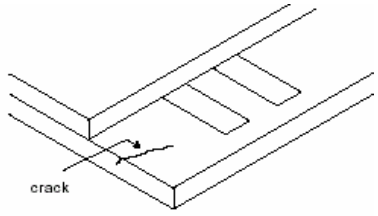
4.2. Cosmetic Defect

<table>
<tr><th>Item No</th><th>Items to be inspected</th><th>Inspection Standard</th><th>Classification of defects</th></tr>
<tr><td>4.2.2</td><td>Line defect
Black line,
White line,
Foreign material under polarizer,</td><td>
<table>
<tr><th colspan="2">Size(mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th rowspan="2">L(Length)</th><th rowspan="2">W(Width)</th><th colspan="3">Zone</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Ignore</td><td>W≤0.02</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>L≤3.0</td><td>0.02＜W≤0.03</td><td colspan="2">2</td></tr>
<tr><td>L≤2.0</td><td>0.03＜W≤0.05</td><td colspan="2">1</td></tr>
<tr><td></td><td>0.05＜W</td><td colspan="2">Define as spot defect</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>4.2.3</td><td>Polarizer scratch</td><td>If the Polarizer scratch can be seen after mobile phone cover assembling or in the operating condition, judge by the line defect of 4.2.2.
If the Polarizer scratch can be seen only in non-operating condition or some special angle, judge by the following.
<table>
<tr><th colspan="2">Size(mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th rowspan="2">L(Length)</th><th rowspan="2">W(Width)</th><th colspan="3">Zone</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Ignore</td><td>W≤0.03</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>5.0＜L≤10.0</td><td>0.03＜W≤0.05</td><td colspan="2">2</td></tr>
<tr><td>L≤5.0</td><td>0.05＜W≤0.08</td><td colspan="2">1</td></tr>
<tr><td></td><td>0.08＜W</td><td colspan="2">0</td></tr>
</table>
</td><td>Minor</td></tr>
<tr><td>4.2.4</td><td>Polarize
Air bubble</td><td>Air bubbles between glass & polarizer
<table>
<tr><th rowspan="2">2. Zone
Size(mm)</th><th colspan="3">Acceptable Qty</th></tr>
<tr><th>A</th><th>B</th><th>C</th></tr>
<tr><td>Φ≤0.2</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.20＜Φ≤0.30</td><td colspan="2">2</td></tr>
<tr><td>0.30＜Φ≤0.50</td><td colspan="2">1</td></tr>
<tr><td>0.50＜Φ</td><td colspan="2">0</td></tr>
</table>
</td><td>Minor</td></tr>
</table>

4.3. Cosmetic Defect

<table>
<tr><th>Item No</th><th>Items to be inspected</th><th>Inspection Standard</th><th>Classification of defects</th></tr>
<tr><td rowspan="3">4.3.5</td><td rowspan="3">Glass defect</td><td>(i) Chips on corner
 

<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>≤2.0</td><td>≤S</td><td>Disregard</td></tr></table>Notes: S=contact pad length
Chips on the corner of terminal shall not be allowed to extend into the ITO pad or expose perimeter seal.</td><td>Minor</td></tr>
<tr><td>(ii)Usual surface cracks
 

<table><tr><th>X</th><th>Y</th><th>Z</th></tr><tr><td>≤3.0</td><td><Inner border line of the seal</td><td>Disregard</td></tr></table></td><td>Minor</td></tr>
<tr><td>(iii) Crack
Cracks tend to break are not allowed.
 
</td><td>Major</td></tr>
<tr><td>4.3.6</td><td>Parts alignment</td><td>1) Not allow IC and FPC/heat-seal lead width is more than 50% beyond lead pattern.
2) Not allow chip or solder component is off center more than 50% of the pad outline.</td><td>Minor</td></tr>
<tr><td>4.3.7</td><td>SMT</td><td>According to the <Acceptability of electronic assemblies> IPC-A-610C class 2 standard. Component missing or function defect are Major defect, the others are Minor defect.</td><td></td></tr>
</table>

■ PRECAUTIONS FOR USING LCD MODULES

1 Handing Precautions

1.1 The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.

1.2 If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.

1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).

1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air.

1.5 If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents

- Isopropyl alcohol
- Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

1.6 Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.

- Water
- Ketone
- Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contact with oil and fats.

1.7 Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.

1.8 Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.

1.9 Do not attempt to disassemble or process the LCD module.

1.10 NC terminal should be open. Do not connect anything.

1.11 If the logic circuit power is off, do not apply the input signals.

1.12 Electro-Static Discharge Control，Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

- Before removing LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
- Tools required for assembling, such as soldering irons, must be properly grounded. Make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
- To reduce the amount of static electricity generated, do not conduct assembling

and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dry. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.

- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

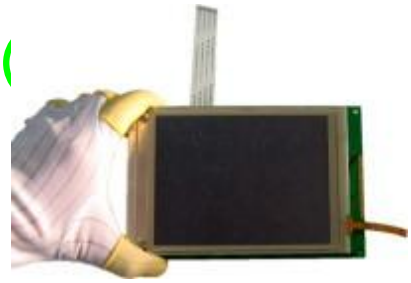
1.13 Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

- Do not alter, modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- Do not damage or modify the pattern writing on the printed circuit board.
- Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist the LCM.

2 Handling precaution for LCM

2.1 LCM is easy to be damaged. Please note below and be careful for handling.

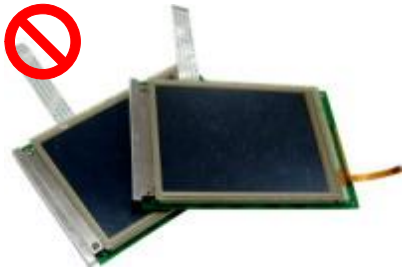
2.2 Correct handling:



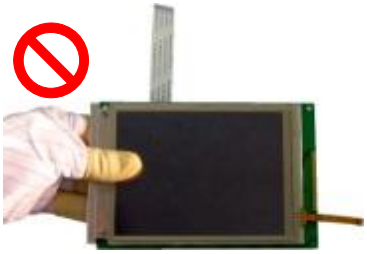
As above picture, please handle with anti-static gloves around LCM edges.

2.3 Incorrect handling:

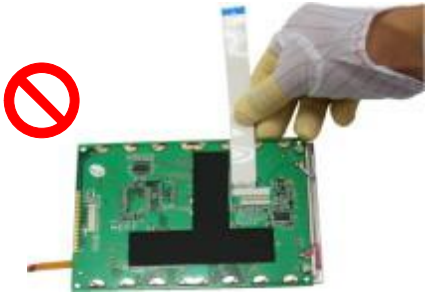
Please don't touch IC directly.



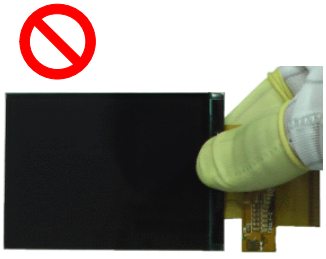
Please don't stack LCM.



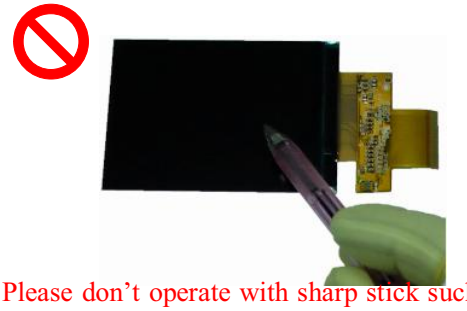
Please don't hold the surface of panel.



Please don't stretch interface of output, such as FPC cable.



Please don't hold the surface of IC.



Please don't operate with sharp stick such as pens.

3 Storage Precautions

3.1 When storing the LCD modules, the following precaution are necessary.

3.1.1 Store them in a sealed polyethylene bag. If properly sealed, there is no need for the desiccant.

3.1.2 Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40%RH and 60%RH.

3.1.3 The polarizer surface should not come in contact with any other objects (We advise you to store them in the anti-static electricity container in which they were shipped).

3.2 Others 其它

3.2.1 Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

3.2.2 If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

3.2.3 To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

3.2.3.1 - Exposed area of the printed circuit board.

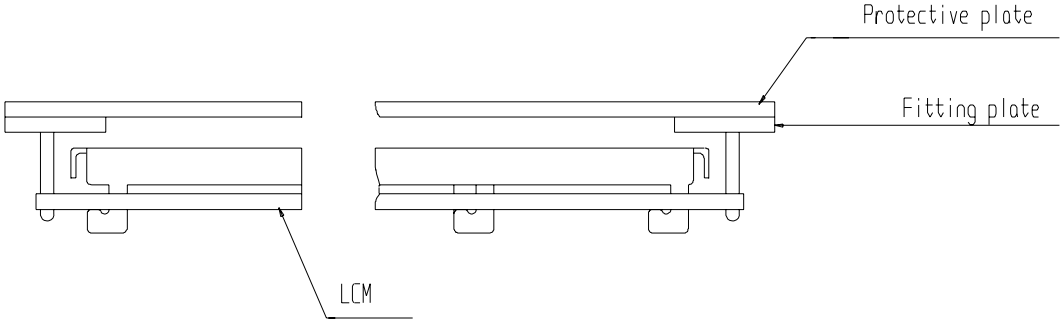
3.2.3.2 -Terminal electrode sections.

4 USING LCD MODULES

4.1 Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

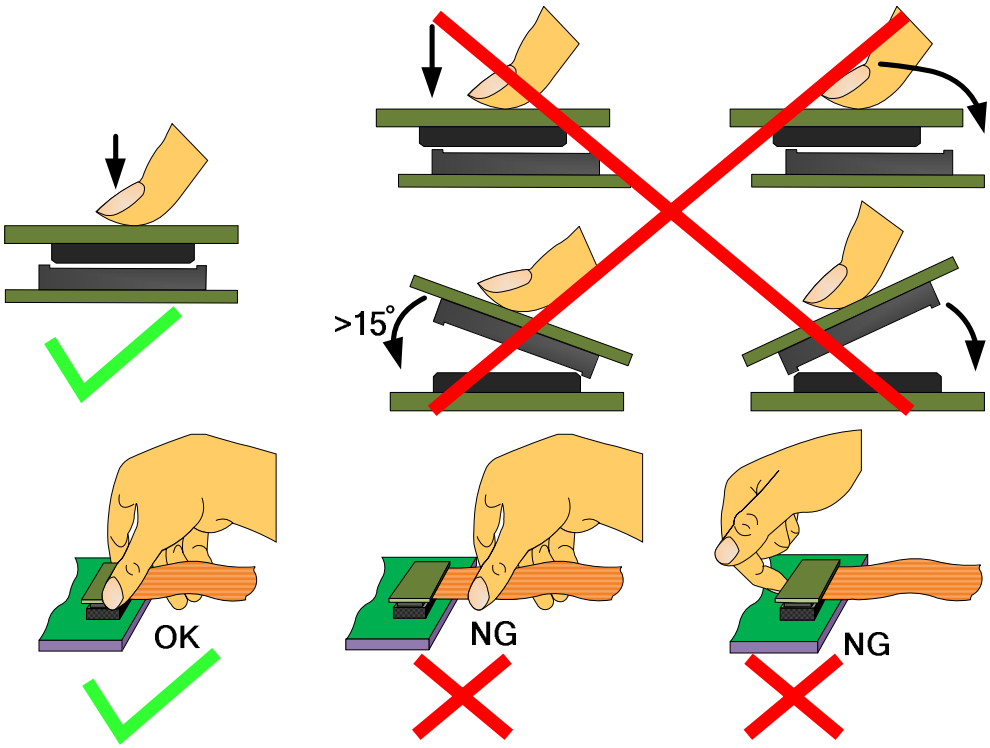
4.1.1 Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



4.1.2 When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ±0.1mm.

4.2 Precaution for assemble the module with BTB connector:

Please note the position of the male and female connector position, don't assemble or assemble like the method which the following picture shows



4.3 Precaution for soldering the LCM

	Manual soldering	Machine drag soldering	Machine press soldering
No RoHS Product	290°C ~350°C. Time : 3-5S.	330°C ~350°C. Speed : 15-17 mm/s.	300°C ~330°C. Time : 3-6S. Press: 0.8~1.2Mpa
RoHS Product	340°C ~370°C. Time : 3-5S.	350°C ~370°C. Speed : 15-17 mm/s.	330°C ~360°C. Time : 3-6S. Press: 0.8~1.2Mpa

4.3.1 If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation (This does not apply in the case of a non-halogen type of flux). It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.

4.3.2 When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.

4.3.3 When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

4.4 Precautions for Operation

4.4.1 Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.

4.4.2 It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

4.4.3 Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operating temperature.

4.4.4 If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.

4.4.5 A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature, 50%RH or less is required.

4.4.6 Input logic voltage before apply analog high voltage such as LCD driving voltage when power on. Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive/negative voltage becomes stable.

4.4.7 Please keep the temperature within the specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.

4.5 Safety

4.5.1 It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.

4.5.2 If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

4. 6 Limited Warranty

Unless agreed between Multi-Inno and the customer, Multi-Inno will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with Multi-Inno LCD acceptance standards (copies available upon request) for a period of one year from date of production. Cosmetic/visual defects must be returned to Multi-Inno within 90 days of shipment. Confirmation of such date shall be based on data code on product. The warranty liability of Multi-Inno limited to repair and/or replace on the terms set forth above. Multi-Inno will not be responsible for any subsequent or consequential events.

4.7 Return LCM under warranty

4.7.1 No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :

4.7.1.1 - Broken LCD glass.

4.7.1.2 - PCB eyelet is damaged or modified.

4.7.1.3 -PCB conductors damaged.

4.7.1.4 - Circuit modified in any way, including addition of components.

4.7.1.5 - PCB tampered with by grinding, engraving or painting varnish.

4.7.1.6 - Soldering to or modifying the bezel in any manner.

4.7.2 Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet, conductors and terminals.

■ PACKING SPECIFICATION

Please consult our technical department for detail information.

■ PRIOR CONSULT MATTER

1 For Multi-Inno standard products, we keep the right to change material, process ... for improving the product property without prior notice to our customer.

2 For OEM products, if any changes are needed which may affect the product property, we will consult with our customer in advance.

3 If you have special requirement about reliability condition, please let us know before you start the test on our samples.